

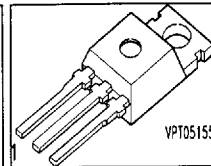
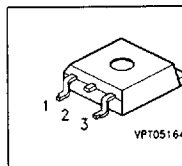
### SIPMOS® Power Transistor

#### Features

- N channel
- Enhancement mode
- Avalanche rated
- Logic Level
- $dv/dt$  rated
- 175 °C operating temperature

#### Product Summary

Drain source voltage	$V_{DS}$	55	V
Drain-Source on-state resistance	$R_{DS(on)}$	0.026	$\Omega$
Continuous drain current	$I_D$	28	A



Type	Package	Ordering Code	Packaging
BUZ103SL	P-TO220-3-1	Q67040-S4008-A2	Tube
BUZ103SL E3045A	P-TO263-3-2	Q67040-S4008-A6	Tape and Reel
BUZ103SL E3045	P-TO263-3-2	Q67040-S4008-A5	Tube

Pin 1	Pin 2	Pin 3
G	D	S

#### Maximum Ratings, at $T_j = 25$ °C unless otherwise specified

Parameter	Symbol	Value	Unit
Continuous drain current $T_C = 25$ °C $T_C = 100$ °C	$I_D$	28 20	A
Pulsed drain current $T_C = 25$ °C	$I_{Dpulse}$	112	
Avalanche energy, single pulse $I_D = 28$ A, $V_{DD} = 25$ V, $R_{GS} = 25$ $\Omega$	$E_{AS}$	140	mJ
Avalanche energy, periodic limited by $T_{jmax}$	$E_{AR}$	7.5	
Reverse diode $dv/dt$ $I_S = 28$ A, $V_{DS} = 40$ V, $di/dt = 200$ A/ $\mu$ s, $T_{jmax} = 175$ °C	$dv/dt$	6	kV/ $\mu$ s
Gate source voltage	$V_{GS}$	-20	V
Power dissipation $T_C = 25$ °C	$P_{tot}$	75	W
Operating and storage temperature	$T_j, T_{stg}$	-55... +175	°C
IEC climatic category; DIN IEC 68-1		55/175/56	

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**Thermal Characteristics**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>Characteristics</b>					
Thermal resistance, junction - case	$R_{thJC}$	-	-	2	K/W
Thermal resistance, junction - ambient, leded	$R_{thJA}$	-	-	62	
SMD version, device on PCB: @ min. footprint @ 6 cm <sup>2</sup> cooling area <sup>1</sup> )	$R_{thJA}$	-	-	62 40	

**Electrical Characteristics, at  $T_j = 25\text{ }^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>Static Characteristics</b>					
Drain- source breakdown voltage $V_{GS} = 0\text{ V}$ , $I_D = 0.25\text{ mA}$	$V_{(BR)DSS}$	55	-	-	V
Gate threshold voltage, $V_{GS} = V_{DS}$ $I_D = 50\text{ }\mu\text{A}$	$V_{GS(th)}$	1.2	1.6	2	
Zero gate voltage drain current $V_{DS} = 50\text{ V}$ , $V_{GS} = 0\text{ V}$ , $T_j = 25\text{ }^\circ\text{C}$ $V_{DS} = 50\text{ V}$ , $V_{GS} = 0\text{ V}$ , $T_j = 150\text{ }^\circ\text{C}$	$I_{DSS}$	-	0.1	1 100	$\mu\text{A}$
Gate-source leakage current $V_{GS} = 20\text{ V}$ , $V_{DS} = 0\text{ V}$	$I_{GSS}$	-	10	100	
Drain-Source on-state resistance $V_{GS} = 4.5\text{ V}$ , $I_D = 20\text{ A}$ $V_{GS} = 10\text{ V}$ , $I_D = 20\text{ A}$	$R_{DS(on)}$	-	0.04 0.0235	0.044 0.026	$\Omega$

<sup>1</sup> Device on 40mm\*40mm\*1.5mm epoxy PCB FR4 with 6 cm<sup>2</sup> (one layer, 70 $\mu\text{m}$  thick) copper area for drain connection. PCB is vertical without blown air.

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**Electrical Characteristics, at  $T_j = 25\text{ }^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>Dynamic Characteristics</b>					
Transconductance $V_{DS} \geq 2 \cdot I_D \cdot R_{DS(on)max}$ , $I_D = 20\text{ A}$	$g_{fs}$	10	20	-	S
Input capacitance $V_{GS} = 0\text{ V}$ , $V_{DS} = 25\text{ V}$ , $f = 1\text{ MHz}$	$C_{iss}$	-	770	960	pF
Output capacitance $V_{GS} = 0\text{ V}$ , $V_{DS} = 25\text{ V}$ , $f = 1\text{ MHz}$	$C_{oss}$	-	230	300	
Reverse transfer capacitance $V_{GS} = 0\text{ V}$ , $V_{DS} = 25\text{ V}$ , $f = 1\text{ MHz}$	$C_{rss}$	-	130	165	
Turn-on delay time $V_{DD} = 30\text{ V}$ , $V_{GS} = 4.5\text{ V}$ , $I_D = 28\text{ A}$ , $R_G = 6.8\ \Omega$	$t_{d(on)}$	-	10	15	ns
Rise time $V_{DD} = 30\text{ V}$ , $V_{GS} = 4.5\text{ V}$ , $I_D = 28\text{ A}$ , $R_G = 6.8\ \Omega$	$t_r$	-	75	115	
Turn-off delay time $V_{DD} = 30\text{ V}$ , $V_{GS} = 4.5\text{ V}$ , $I_D = 28\text{ A}$ , $R_G = 6.8\ \Omega$	$t_{d(off)}$	-	30	45	
Fall time $V_{DD} = 30\text{ V}$ , $V_{GS} = 4.5\text{ V}$ , $I_D = 28\text{ A}$ , $R_G = 6.8\ \Omega$	$t_f$	-	20	30	

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**Electrical Characteristics, at  $T_j = 25\text{ }^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>Dynamic Characteristics</b>					
Gate to source charge $V_{DD} = 40\text{ V}$ , $I_D = 28\text{ A}$	$Q_{gs}$	-	4	6	nC
Gate to drain charge $V_{DD} = 40\text{ V}$ , $I_D = 28\text{ A}$	$Q_{gd}$	-	12	18	
Gate charge total $V_{DD} = 40\text{ V}$ , $I_D = 28\text{ A}$ , $V_{GS} = 0\text{ to }10\text{ V}$	$Q_g$	-	32	50	
Gate plateau voltage $V_{DD} = 40\text{ V}$ , $I_D = 28\text{ A}$	$V_{(\text{plateau})}$	-	4	-	V

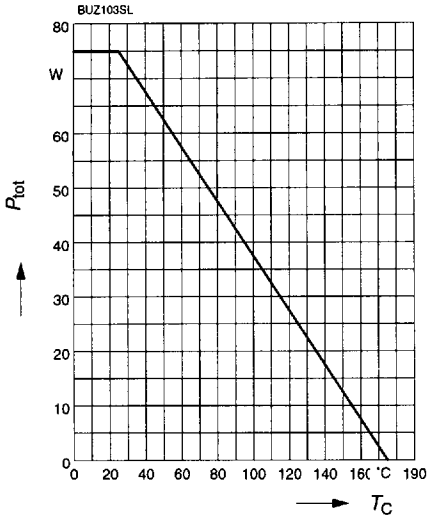
**Reverse Diode**

Inverse diode continuous forward current $T_C = 25\text{ }^\circ\text{C}$	$I_S$	-	-	28	A
Inverse diode direct current, pulsed $T_C = 25\text{ }^\circ\text{C}$	$I_{SM}$	-	-	112	
Inverse diode forward voltage $V_{GS} = 0\text{ V}$ , $I_F = 56\text{ A}$	$V_{SD}$	-	1.1	1.8	V
Reverse recovery time $V_R = 30\text{ V}$ , $I_F = I_S$ , $di_F/dt = 100\text{ A}/\mu\text{s}$	$t_{rr}$	-	60	90	ns
Reverse recovery charge $V_R = 30\text{ V}$ , $I_F = I_S$ , $di_F/dt = 100\text{ A}/\mu\text{s}$	$Q_{rr}$	-	0.15	0.25	$\mu\text{C}$

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**Power Dissipation**

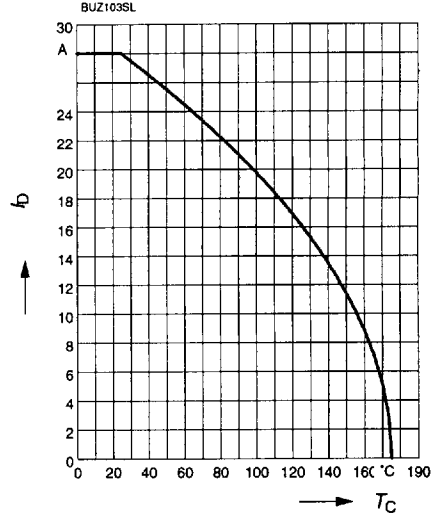
$P_{tot} = f(T_C)$



**Drain current**

$I_D = f(T_C)$

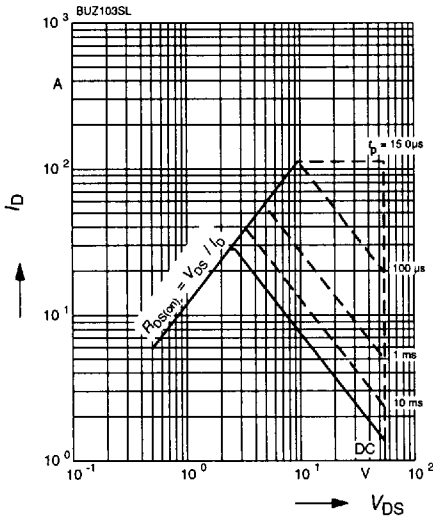
parameter:  $V_{GS} \geq 10\text{ V}$



**Safe operating area**

$I_D = f(V_{DS})$

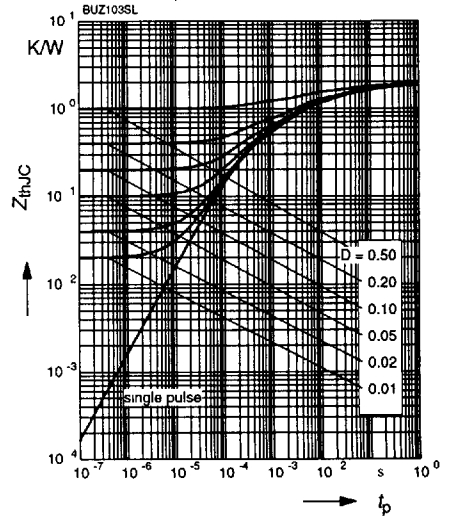
parameter:  $D = 0, T_C = 25\text{ °C}$



**Transient thermal impedance**

$Z_{thJC} = f(t_p)$

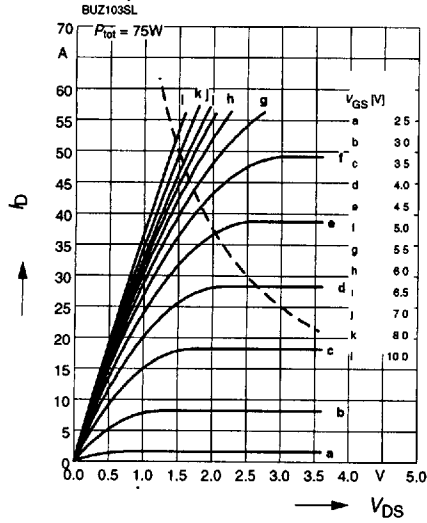
parameter:  $D = t_p/T$



**Typ. output characteristics**

$I_D = f(V_{DS})$

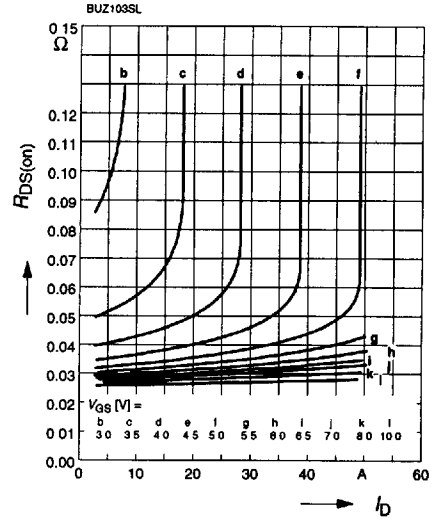
parameter:  $t_p = 80 \mu s$



**Typ. drain-source-on-resistance**

$R_{DS(on)} = f(I_D)$

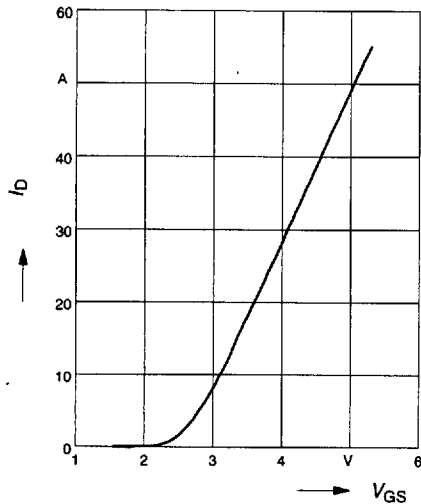
parameter:  $V_{GS}$



**Typ. transfer characteristics**  $I_D = f(V_{GS})$

parameter:  $t_p = 80 \mu s$

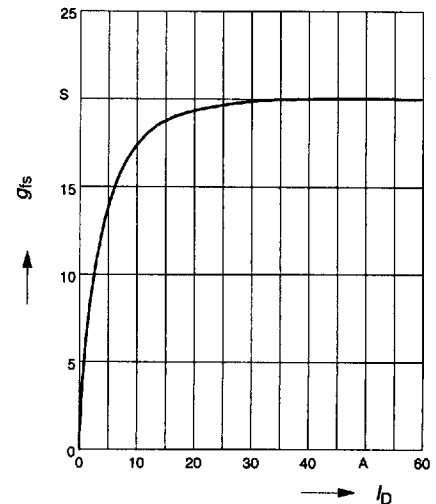
$V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$



**Typ. forward transconductance**

$g_{fs} = f(I_D); T_j = 25^\circ C$

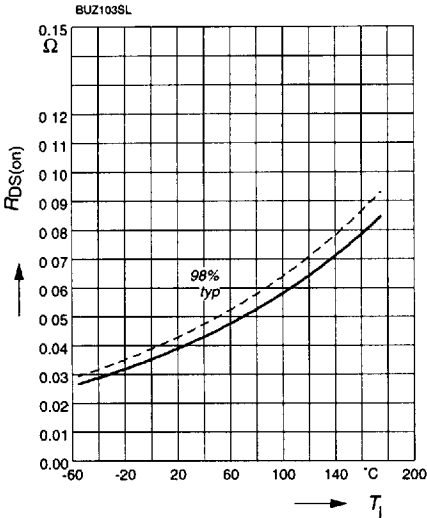
parameter:  $g_{fs}$



**Drain-source on-resistance**

$$R_{DS(on)} = f(T_j)$$

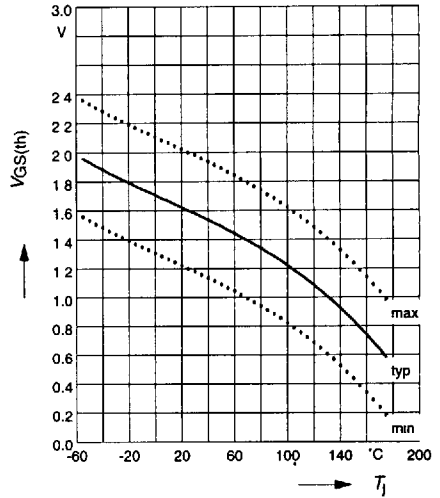
parameter :  $I_D = 20 \text{ A}$ ,  $V_{GS} = 4.5 \text{ V}$



**Gate threshold voltage**

$$V_{GS(th)} = f(T_j)$$

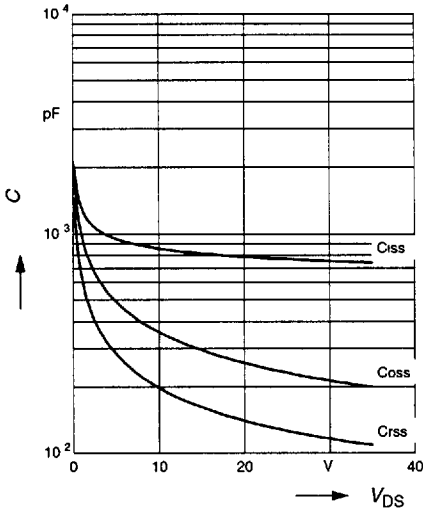
parameter :  $V_{GS} = V_{DS}$ ,  $I_D = 50 \mu\text{A}$



**Typ. capacitances**

$$C = f(V_{DS})$$

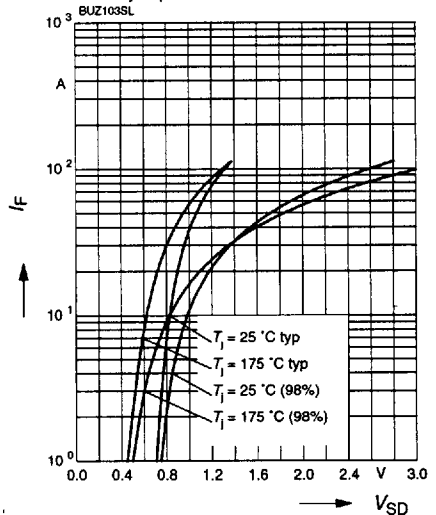
Parameter:  $V_{GS} = 0 \text{ V}$ ,  $f = 1 \text{ MHz}$



**Forward characteristics of reverse diode**

$$I_F = f(V_{SD})$$

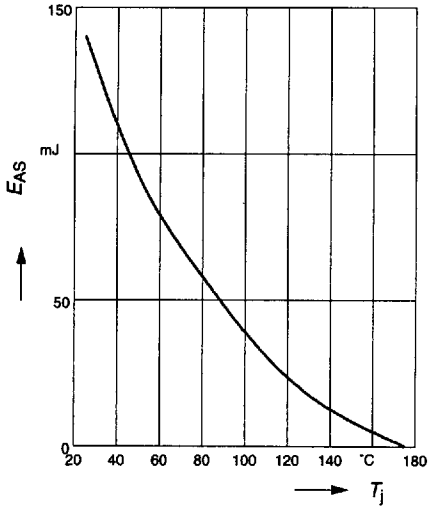
parameter:  $T_j$ ,  $t_p = 80 \mu\text{s}$



**Avalanche Energy  $E_{AS} = f(T_j)$**

parameter:  $I_D = 28\text{ A}$ ,  $V_{DD} = 25\text{ V}$

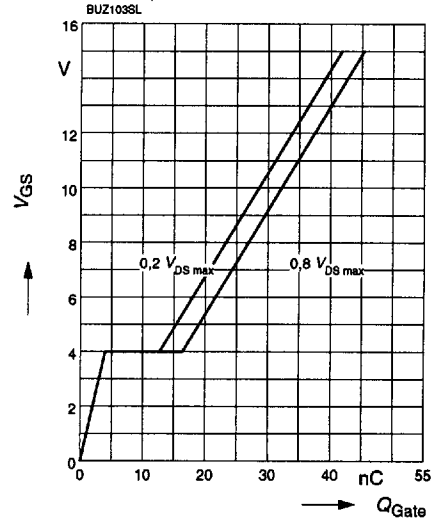
$R_{GS} = 25\ \Omega$



**Typ. gate charge  $V_{GS} = f(Q_{Gate})$**

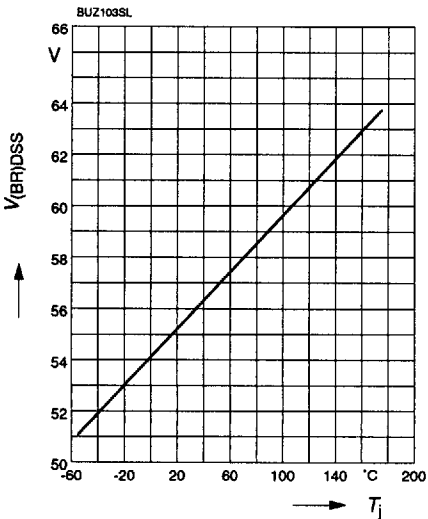
$V_{GS} = f(Q_{Gate})$

parameter:  $I_D\text{ puls} = 28\text{ A}$



**Drain-source breakdown voltage  $V_{(BR)DSS} = f(T_j)$**

$V_{(BR)DSS} = f(T_j)$



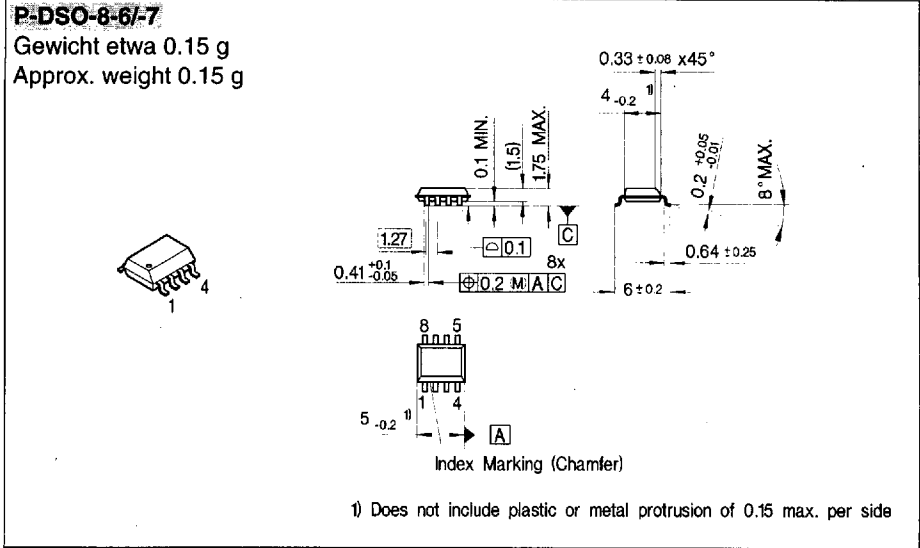


**Gehäusemaßbilder**

(Maße in mm, wenn nicht anders angegeben)

**Package Outlines**

(Dimensions in mm, unless otherwise specified)



**Bild 16**

**Figure 16**

**P-TO218-AA (P-TO218-2-1)**

Gewicht etwa 4.9 g  
Approx. weight 4.9 g

**Bild 17**

**Figure 17**

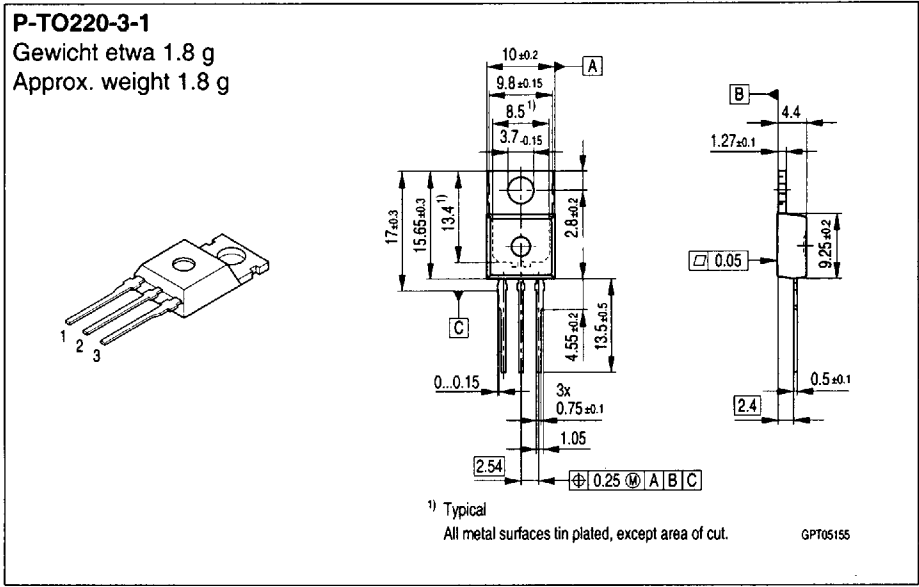


Bild 18

Figure 18

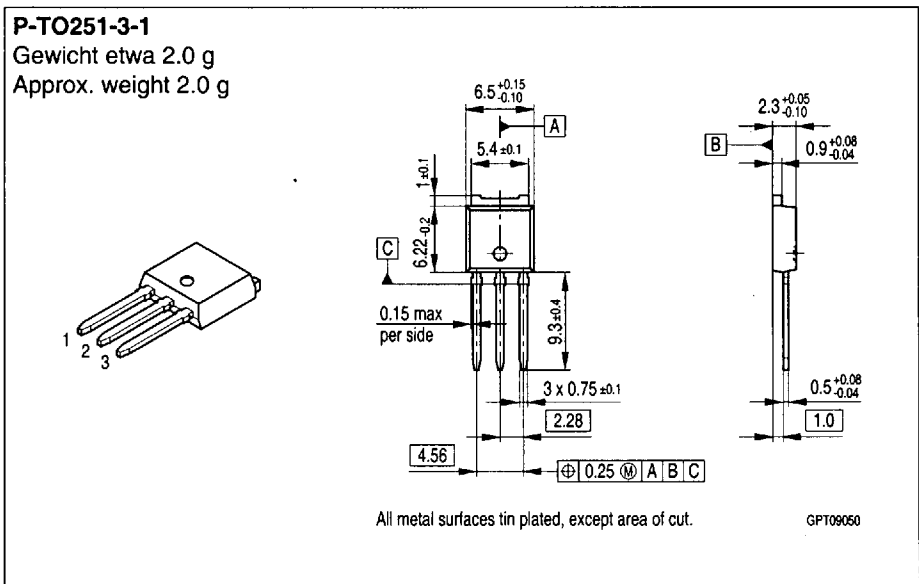
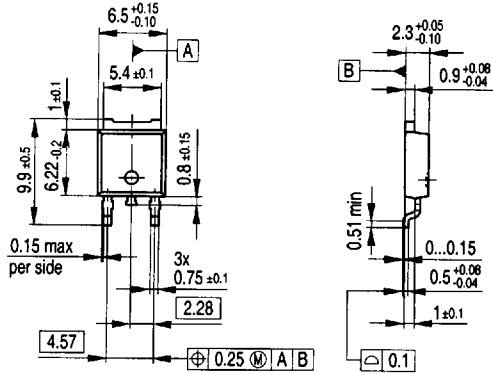
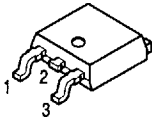


Bild 19

Figure 19

**P-TO252-3-1**

Gewicht etwa 0.38 g  
Approx. weight 0.38 g



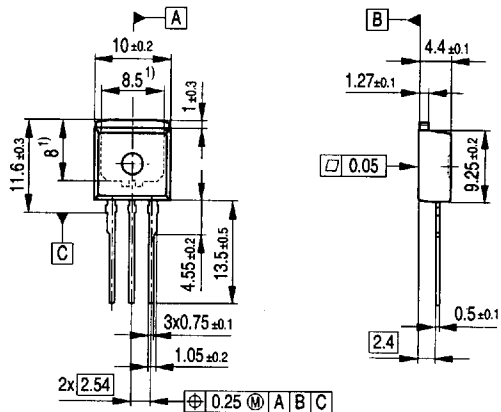
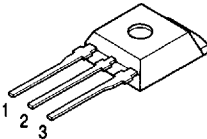
All metal surfaces tin plated, except area of cut.

GPT09051

Bild 20

Figure 20

**P-TO262-3-1/I<sup>2</sup>PAK**



1) Typical

Metal surface min. X = 7.25, Y = 7.35

All metal surfaces tin plated, except area of cut.

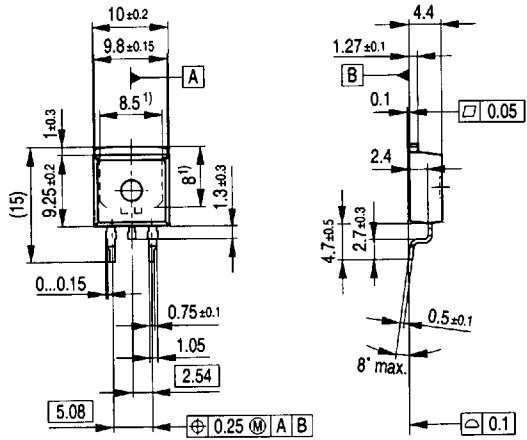
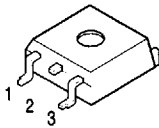
GPT09244

Bild 21

Figure 21

**P-TO263-3-2/D<sup>2</sup>PAK**

Gewicht etwa 1.38 g  
Approx. weight 1.38 g



<sup>1)</sup> Typical  
All metal surfaces tin plated, except area of cut.

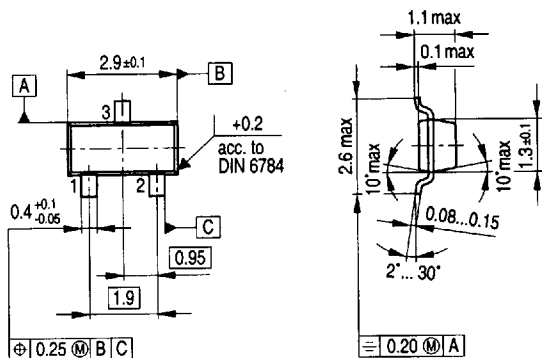
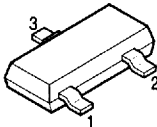
GPT09085

Bild 22

Figure 22

**SOT-23 (P-SOT23-3-1)**

Gewicht etwa 0.01 g  
Approx. weight 0.01 g



GPS05557

Bild 23

Figure 23

**SOT-89**

Gewicht etwa 0.01 g  
Approx. weight 0.01 g

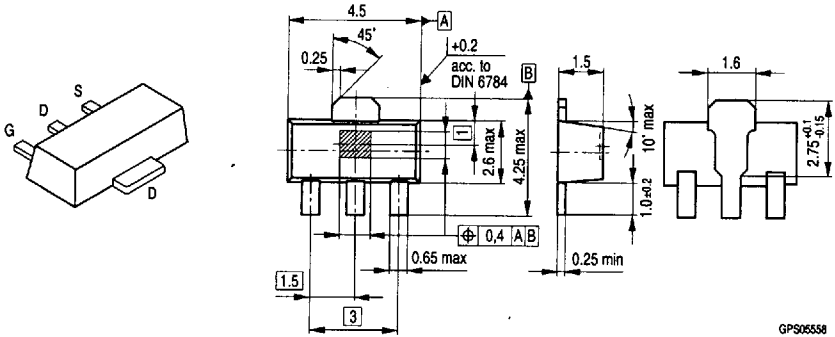


Bild 24

Figure 24

**SOT-223 (P-SOT223-4-1)**

Gewicht etwa 0.15 g  
Approx. weight 0.15 g

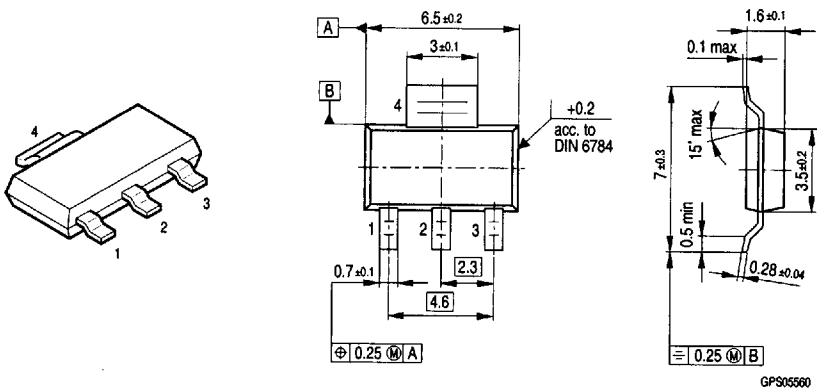
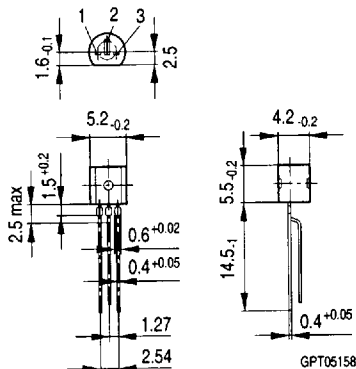
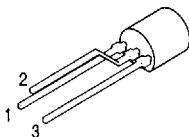


Bild 25

Figure 25

**TO-92**

Gewicht etwa 0.23 g  
Approx. weight 0.23 g

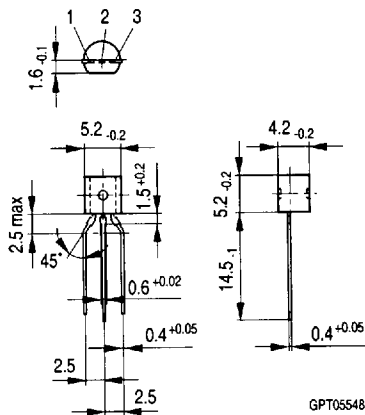
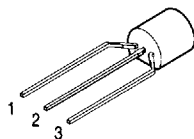


**Bild 26**

**Figure 26**

**TO-92-E6288**

Gewicht etwa 0.23 g  
Approx. weight 0.23 g



**Bild 27**

**Figure 27**

**Sorts of Packing**

Package outlines for tubes, trays etc. are contained in our Data Book "Package Information".

**SMD = Surface Mounted Device**